

SOT684-32(DD)

HVQFN56; thermal enhanced low profile quad flat non-leaded package, dimple wettable flank; 56 terminals; 0.5 mm pitch; 8 mm x 8 mm x 0.9 mm body

6 June 2025

Package information



1 Package summary

Package type descriptive code	HVQFN56
Package style descriptive code	HVQFN (thermal enhanced very thin quad flatpack; no leads)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Manufacturer package code	98ASA01997D

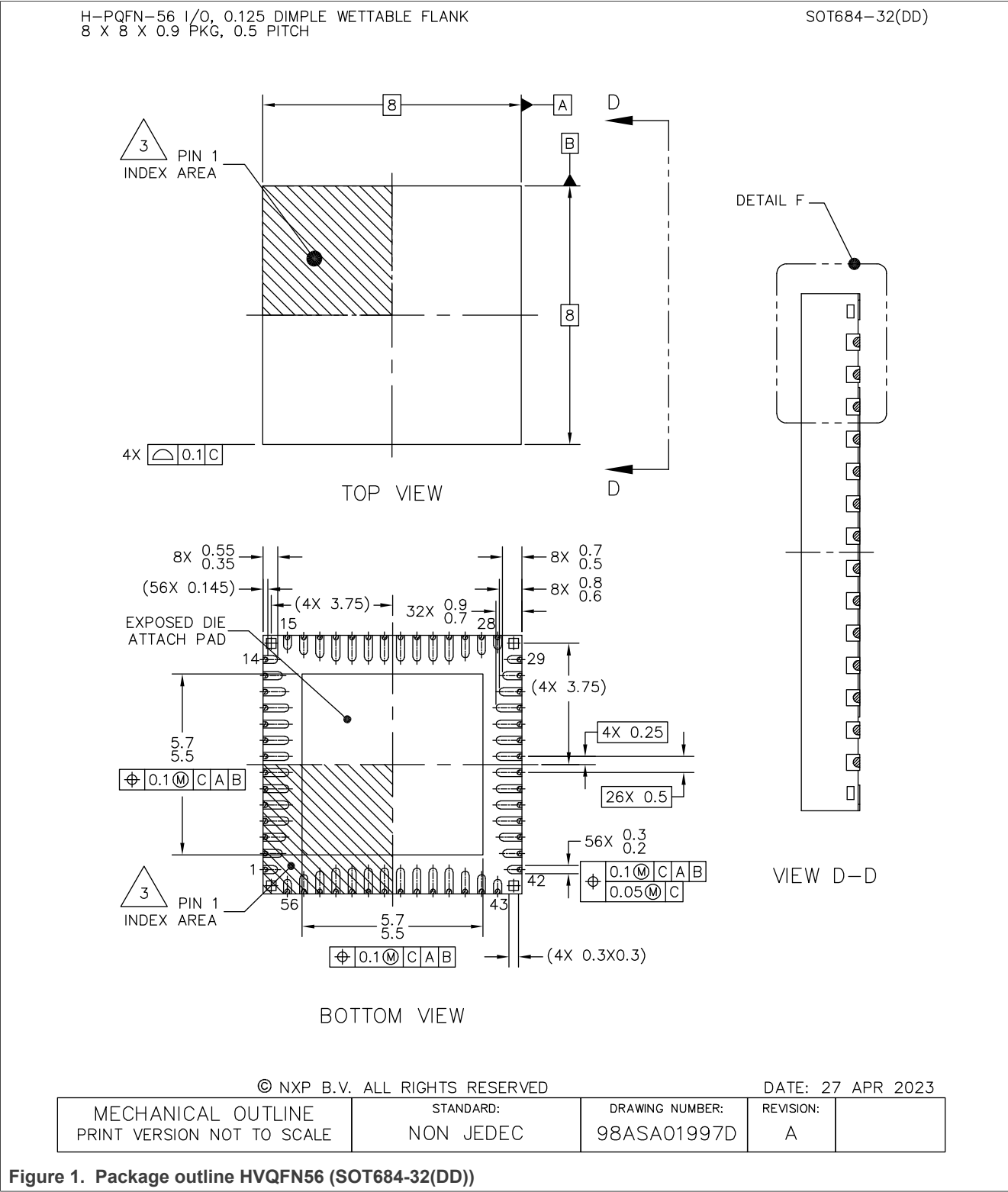
Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	7.9	8	8.1	mm
package width	7.9	8	8.1	mm
package height	0.8	0.9	1	mm
nominal pitch	-	0.5	-	mm
actual quantity of termination	-	56	-	



HVQFN56; thermal enhanced low profile quad flat non-leded package, dimple wettable flank; 56 terminals; 0.5 mm pitch; 8 mm x 8 mm x 0.9 mm body

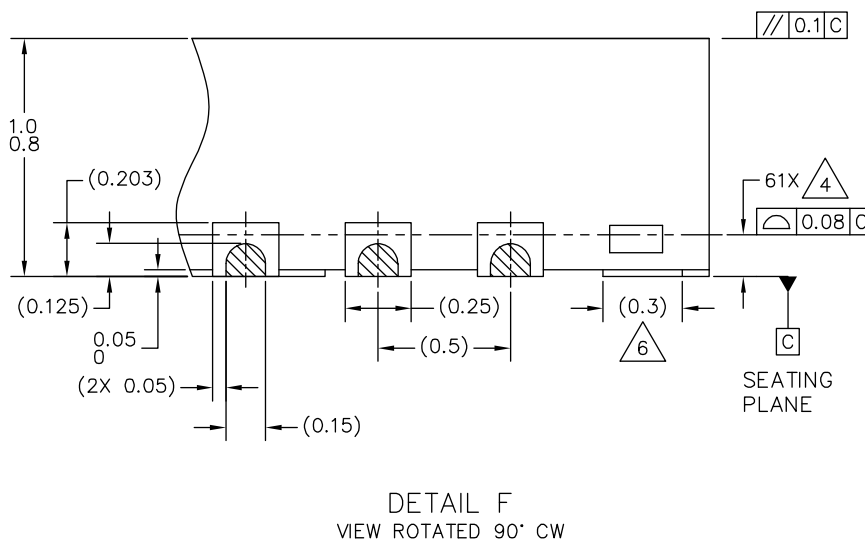
2 Package outline



HVQFN56; thermal enhanced low profile quad flat non-leaded package, dimple wettable flank; 56 terminals; 0.5 mm pitch; 8 mm x 8 mm x 0.9 mm body

H-PQFN-56 I/O, 0.125 DIMPLE WETTABLE FLANK
8 X 8 X 0.9 PKG, 0.5 PITCH

SOT684-32(DD)



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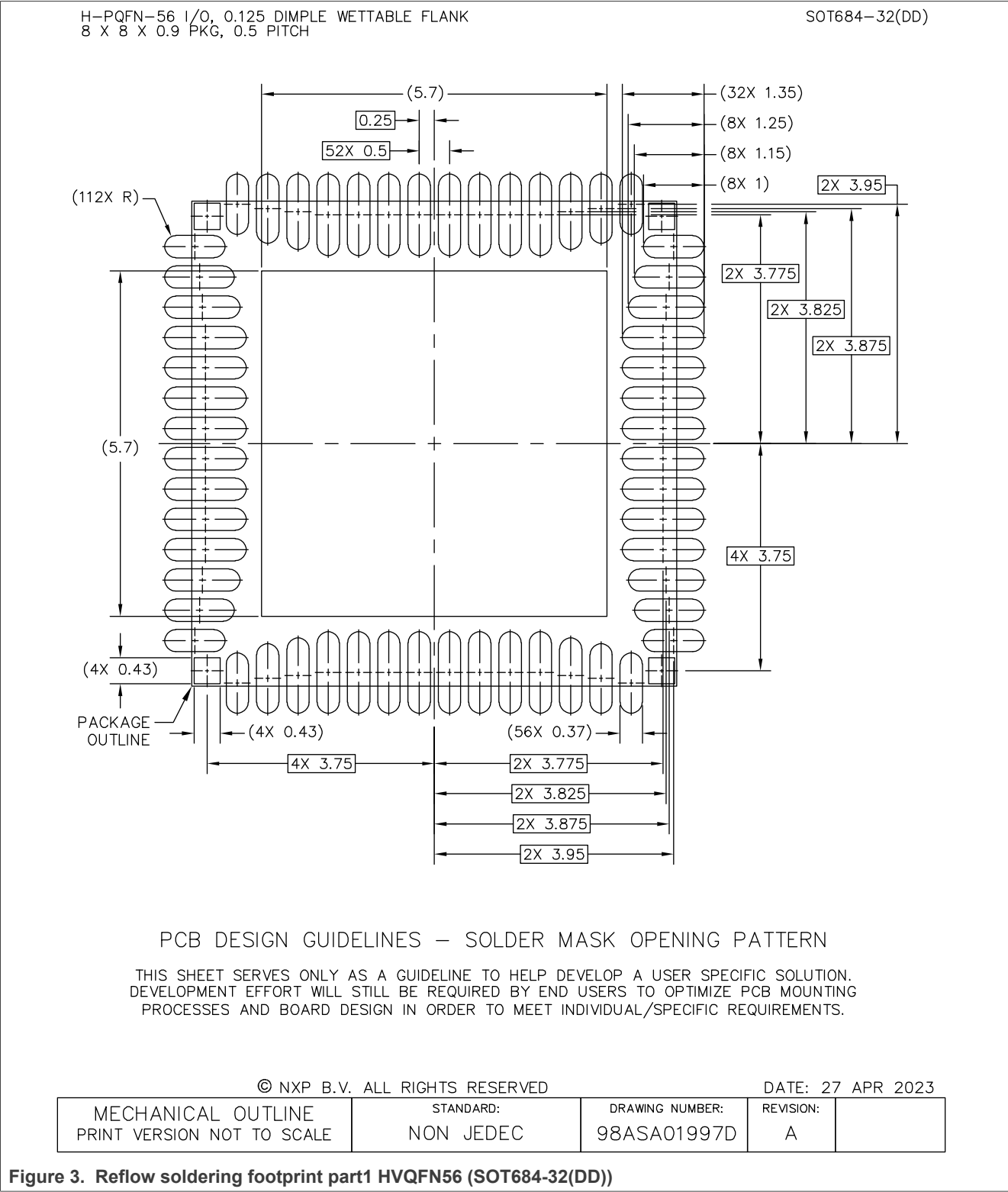
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Figure 2. Package outline detail HVQFN56 (SOT684-32(DD))

HVQFN56; thermal enhanced low profile quad flat non-led package, dimple wettable flank; 56 terminals; 0.5 mm pitch; 8 mm x 8 mm x 0.9 mm body

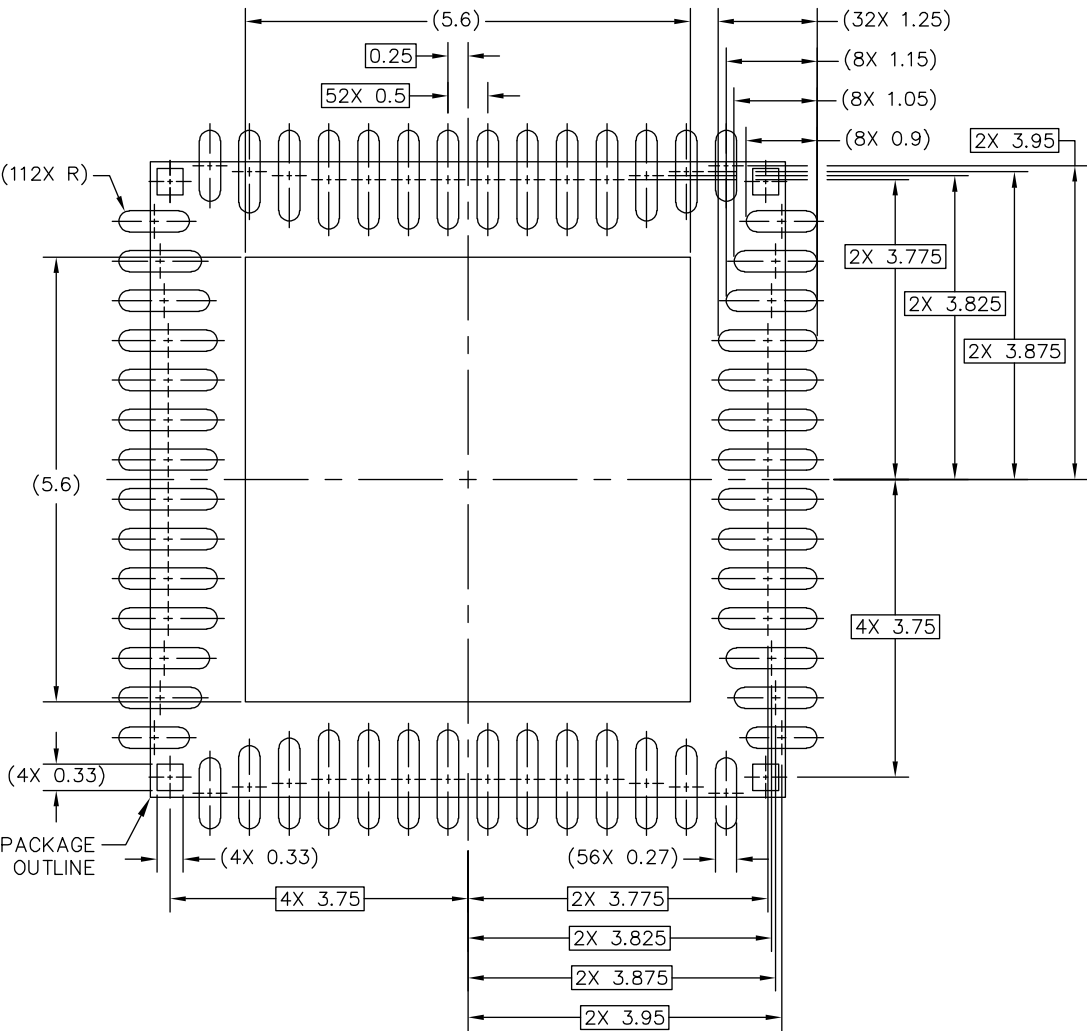
3 Soldering



HVQFN56; thermal enhanced low profile quad flat non-leded package, dimple wettable flank; 56 terminals; 0.5 mm pitch; 8 mm x 8 mm x 0.9 mm body

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PCB DESIGN GUIDELINES – I/O PADS AND SOLDERABLE AREA

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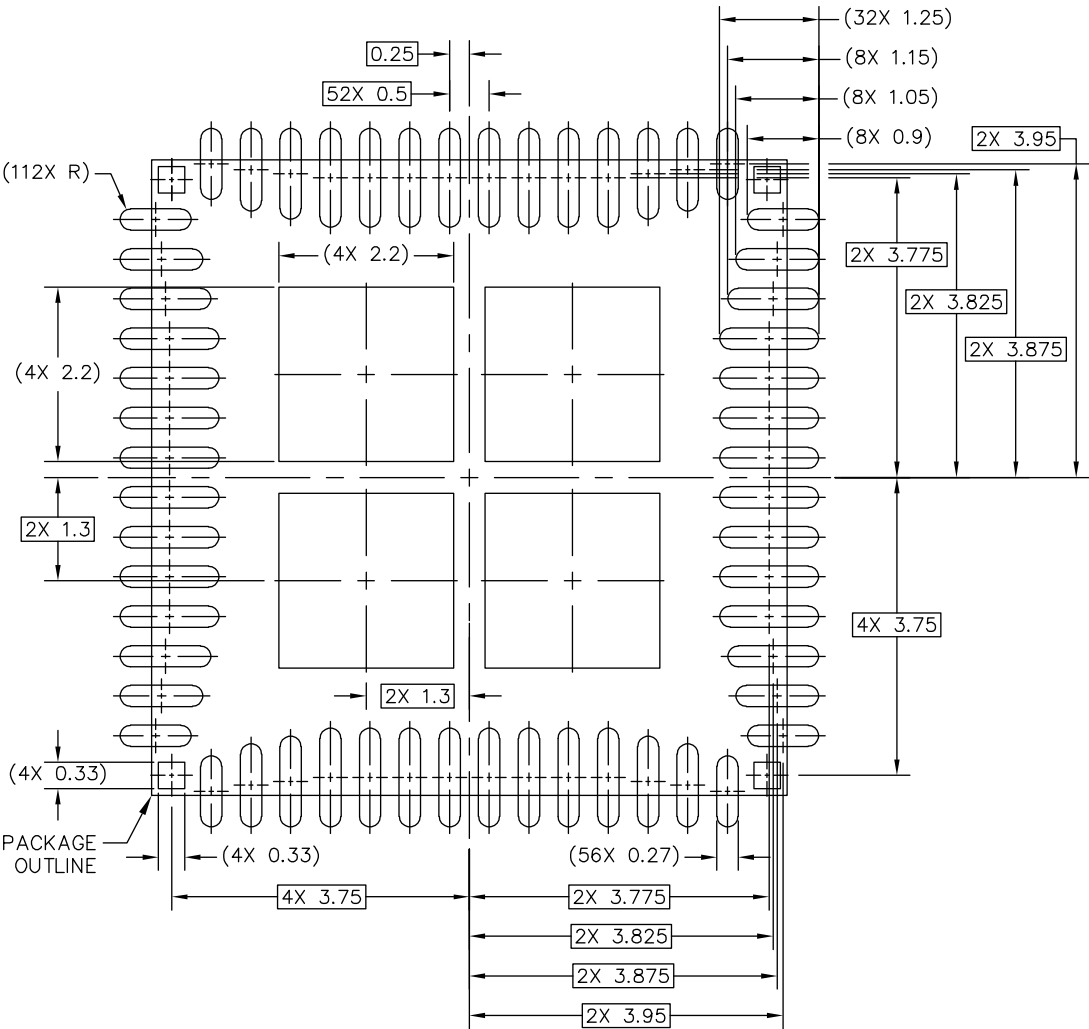
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Figure 4. Reflow soldering footprint part2 HVQFN56 (SOT684-32(DD))

HVQFN56; thermal enhanced low profile quad flat non-ledged package, dimple wettable flank; 56 terminals; 0.5 mm pitch; 8 mm x 8 mm x 0.9 mm body

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RECOMMENDED STENCIL THICKNESS 0.125

PCB DESIGN GUIDELINES – SOLDER PASTE STENCIL

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Figure 5. Reflow soldering footprint part3 HVQFN56 (SOT684-32(DD))

HVQFN56; thermal enhanced low profile quad flat non-leaded package, dimple wettable flank; 56 terminals; 0.5 mm pitch; 8 mm x 8 mm x 0.9 mm body

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NOTES:

- 1. ALL DIMENSIONS IN MILLIMETERS.
- 2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
- 3. PIN 1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
- 4. COPLANARITY APPLIES TO LEADS, DIE ATTACH FLAG AND CORNER NON-FUNCTIONAL PADS.
- 5. MIN. METAL GAP SHOULD BE 0.25 MM.
- 6. ANCHORING PADS.

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Figure 6. Package outline note HVQFN56 (SOT684-32(DD))

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